Thyristors logic level for RCD/ GFI/ LCCB applications

BT168 series

GENERAL DESCRIPTION QUICK REFERENCE DATA

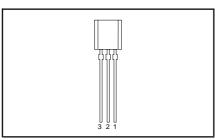
Passivated, sensitive gate thyristors in a plastic envelope, intended for use in Residual Current Devices/ Ground Fault Interrupters/ Leakage Current Circuit Breakers (RCD/ GFI/ LCCB) applications where a minimum I_{GT} limit is needed. These devices may be interfaced directly to microcontrollers, logic integrated circuits and other low power gate trigger circuits.

SYMBOL	PARAMETER	MAX.	MAX.	UNIT
V _{DRM} , V _{RRM} I _{T(AV)} I _{T(RMS)} I _{TSM}	Repetitive peak off-state voltages Average on-state current RMS on-state current Non-repetitive peak on-state current	E 500 0.5 0.8 8	G 600 0.5 0.8 8	V A A A

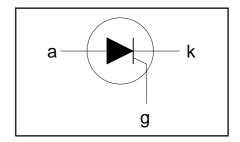
PINNING - TO92 variant

PIN	DESCRIPTION	
1	anode	
2	gate	
3	cathode	

PIN CONFIGURATION



SYMBOL



LIMITING VALUES

Limiting values in accordance with the Absolute Maximum System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MA	λX.	UNIT
V_{DRM}, V_{RRM}	Repetitive peak off-state voltages		-	E 500 ¹	G 600 ¹	V
I _{T(AV)}	Average on-state current	half sine wave;	-	0	.5	A
I _{T(RMS)} I _{TSM}	RMS on-state current Non-repetitive peak on-state current	$T_{lead} \le 83 ^{\circ}\text{C}$ all conduction angles t = 10 ms t = 8.3 ms half sine wave; $T_i = 25 ^{\circ}\text{C}$ prior to surge	- - -		.8 3 9	A A A
l²t dl _⊤ /dt	l²t for fusing Repetitive rate of rise of on-state current after	t = 10 ms $I_{TM} = 2 \text{ A}; I_G = 10 \text{ mA};$ $dI_G/dt = 100 \text{ mA/}\mu\text{s}$	- -	-	32 0	A²s A/μs
I _{GM} V _{GM} V _{RGM} P _{GM} P _{G(AV)} T _{stg} T _j	triggering Peak gate current Peak gate voltage Peak reverse gate voltage Peak gate power Average gate power Storage temperature Operating junction temperature	over any 20 ms period	- - - - -40 -	0 1	1 5 5 2 .1 50 25	۵°, ۵°, ۵°,

¹ Although not recommended, off-state voltages up to 800V may be applied without damage, but the thyristor may switch to the on-state. The rate of rise of current should not exceed 15 A/ μ s.

Philips Semiconductors Product specification

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THERMAL RESISTANCES

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
R _{th j-lead}	Thermal resistance junction to lead		-	-	60	K/W
R _{th j-a}	Thermal resistance junction to ambient	pcb mounted; lead length = 4mm	-	150	-	K/W

STATIC CHARACTERISTICS

T_i = 25 °C unless otherwise stated

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I _{GT}	Gate trigger current	$V_D = 12 \text{ V}$; $I_T = 10 \text{ mA}$; gate open circuit	20	50	200	μΑ
Լ լ	Latching current	$V_D = 12 \text{ V}; I_{GT} = 0.5 \text{ mA}; R_{GK} = 1 \text{ k}\Omega$	-	2	6	mA
l I _H	Holding current	$V_D = 12 \text{ V}; I_{GT} = 0.5 \text{ mA}; R_{GK} = 1 \text{ k}\Omega$	-	2	5	mΑ
Ϋ́Τ	On-state voltage	$I_T = 1 A$	-	1.2	1.35	V
V _{GT}	Gate trigger voltage	$\dot{V}_D = 12 \text{ V}$; $I_T = 10 \text{ mA}$; gate open circuit	-	0.5	0.8	V
		$V_D = V_{DRM(max)}$; $I_T = 10 \text{ mA}$; $T_j = 125 \text{ °C}$;	0.2	0.3	-	V
		gate open circuit				
I _D , I _R	Off-state leakage current	$ \begin{vmatrix} \vec{V}_D = \vec{V}_{DRM(max)}; \ \vec{V}_R = \vec{V}_{RRM(max)}; \ \vec{T}_j = 125 \ ^{\circ}C; \ \vec{R}_{GK} = 1 \ k\Omega $	-	0.05	0.1	mA

DYNAMIC CHARACTERISTICS

T_i = 25 °C unless otherwise stated

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
OTHIDOL	I ANAMETEN	CONDITIONS	141114.		WAA.	OIIII
dV _D /dt	Critical rate of rise of	$V_{DM} = 67\% V_{DRM(max)}; T_j = 125 °C;$	500	800	-	V/μs
t _{gt}	off-state voltage Gate controlled turn-on	exponential waveform; $R_{GK} = 1 \text{ k}\Omega$ $I_{TM} = 2 \text{ A}$; $V_D = V_{DRM(max)}$; $I_G = 10 \text{ mA}$;	-	2	-	μs
t _q	time Circuit commutated	$ dI_G/dt = 0.1 \text{ A/}\mu\text{s}$ $ V_D = 67\% \text{ V}_{DRM(max)}; \text{ T}_i = 125 \text{ °C};$ $ I_{TM} = 1.6 \text{ A}; \text{ V}_R = 35 \text{ V}; \text{ d}I_{TM}/dt = 30 \text{ A/}\mu\text{s};$	-	100	-	μs
	turn-off time	$I_{TM} = 1.6 \text{ A}; V_R = 35 \text{ V}; dI_{TM}/dt = 30 \text{ A/}\mu\text{s}; dV_D/dt = 2 \text{ V/}\mu\text{s}; R_{GK} = 1 \text{ k}\Omega$				

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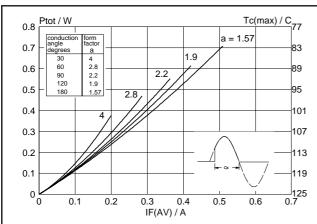


Fig.1. Maximum on-state dissipation, P_{tot} , versus average on-state current, $I_{T(AV)}$, where $a = form \ factor = I_{T(RMS)} / I_{T(AV)}$.

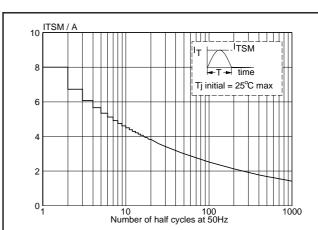


Fig.4. Maximum permissible non-repetitive peak on-state current I_{TSM} , versus number of cycles, for sinusoidal currents, f = 50 Hz.

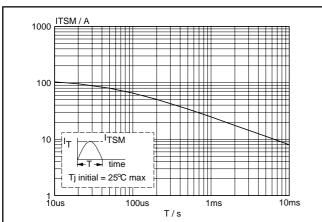


Fig.2. Maximum permissible non-repetitive peak on-state current I_{TSM} , versus pulse width t_p , for sinusoidal currents, $\dot{t}_p \leq 10$ ms.

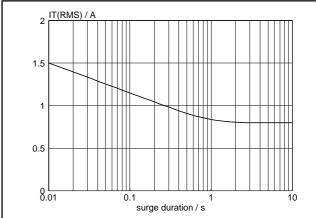


Fig.5. Maximum permissible repetitive rms on-state current I_{T(RMS)}, versus surge duration, for sinusoidal currents, f = 50 Hz; $T_{lead} \le 83$ °C.

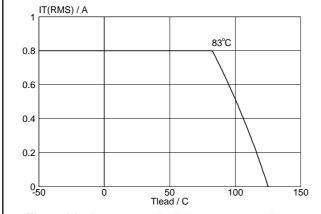


Fig.3. Maximum permissible rms current $I_{\text{T(RMS)}}$, versus lead temperature, T_{lead} .

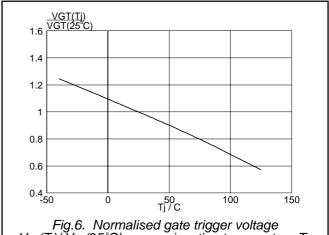
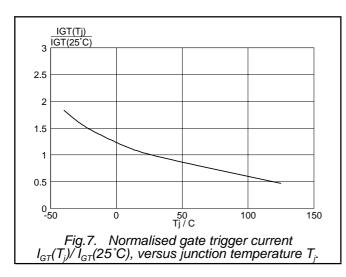


Fig.6. Normalised gate trigger voltage $V_{GT}(T_j)/V_{GT}(25^{\circ}C)$, versus junction temperature T_{j} .

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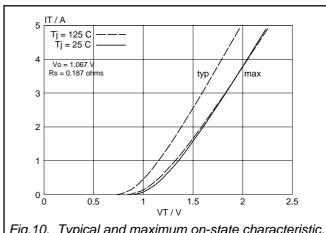
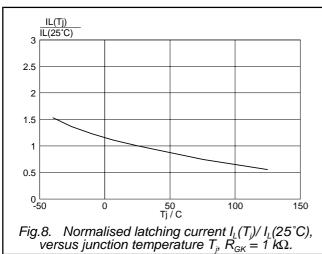


Fig. 10. Typical and maximum on-state characteristic.



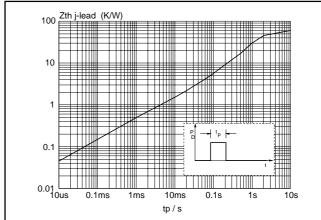
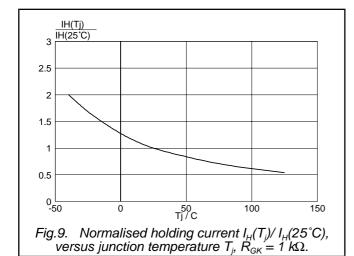


Fig.11. Transient thermal impedance $Z_{th j-lead}$, versus pulse width $t_{\rm p}$



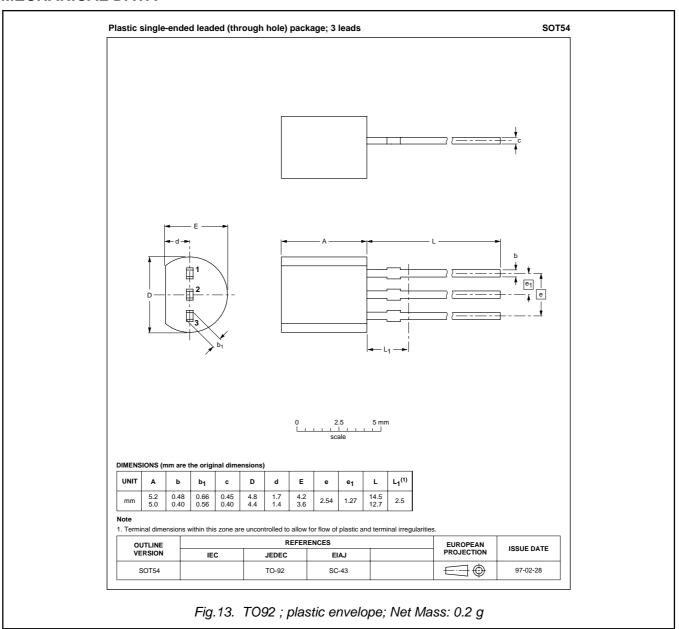
dVD/dt (V/us) 10000 1000 100 Tj/C

Fig.12. Typical, critical rate of rise of off-state voltage, $d\dot{V}_D/dt$ versus junction temperature T_{i}

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MECHANICAL DATA



Notes

1. Epoxy meets UL94 V0 at 1/8".

Philips Semiconductors Product specification

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DEFINITIONS

DATA SHEET STATUS					
DATA SHEET STATUS ²	PRODUCT STATUS ³	DEFINITIONS			
Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice			
Preliminary data	Qualification	This data sheet contains data from the preliminary specification. Supplementary data will be published at a later date. Philips Semiconductors reserves the right to change the specification without notice, in ordere to improve the design and supply the best possible product			
Product data	Production	This data sheet contains data from the product specification. Philips Semiconductors reserves the right to make changes at any time in order to improve the design, manufacturing and supply. Changes will be communicated according to the Customer Product/Process Change Notification (CPCN) procedure SNW-SQ-650A			

Limiting values

Limiting values are given in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of this specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

Application information

Where application information is given, it is advisory and does not form part of the specification.

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² Please consult the most recently issued datasheet before initiating or completing a design.

³ The product status of the device(s) described in this datasheet may have changed since this datasheet was published. The latest information is available on the Internet at URL http://www.semiconductors.philips.com.